

DATE: 7 March, 2018

PCN #: 2300

PCN Title: Qualification of Additional Assembly and Test Sites

## Dear Customer:

This is an announcement of change(s) to products that are currently being offered by Diodes Incorporated.

We request that you acknowledge receipt of this notification within 30 days of the date of this PCN. If you require samples for evaluation purposes, please make a request within 30 days as well. Otherwise, samples may not be built prior to this change. Please refer to the implementation date of this change as it is stated in the attached PCN form. Please contact your local Diodes sales representative to acknowledge receipt of this PCN and for any sample requests.

The changes announced in this PCN will not be implemented earlier than 90 days from the notification date stated in the attached PCN form.

Previously agreed upon customer specific change process requirements or device specific requirements will be addressed separately.

For questions or clarification regarding this PCN, please contact your local Diodes sales representative.

Sincerely,

Diodes Incorporated PCN Team

Rel Date: 2/10/2016



# PRODUCT CHANGE NOTICE

### PCN-2300 REV 1

Rel Date: 2/10/2016

Notification Date:	Implementation Date:	Product Family:	Change Type:	PCN #:		
7 March, 2018	7 June, 2018	Discrete	Assembly and Test Site	2300		
TITLE						
Qualification of Additional Assembly and Test Sites						

#### **DESCRIPTION OF CHANGE**

This PCN is being issued to notify customers that in order to assure continuity of supply, Diodes has qualified the additional assembly and test site, Tianshui Huatian Electronic Group Co., Ltd. (HTME) in China, for selected TO220AB or TO263AB packaged products and, Eris Technology Corp. (ERIS) in Taiwan, for selected DO-214AC (SMA) packaged products.

The package outline dimensions (POD) remain the same, but the appearance is slightly different on the parts made by HTME for TO220AB and TO263AB packages. Please refer to the details (with different options A and B) in Table 1 below.

Full electrical characterization and high reliability testing has been completed on representative part numbers to ensure there is no change to device functionality or electrical specifications in the datasheet. See attached (embedded) qualification report.

#### **IMPACT**

Table 1: Additional Assembly and Test Site, Tianshui Huatian Electronic Group Co., Ltd. (HTME) in China Table 2: Additional Assembly and Test Site, Eris Technology Corp. (ERIS) in Taiwan

## **PRODUCTS AFFECTED**

See Tables 1 - 2 below.

WEB LINKS					
Manufacturer's Notice:	https://www.diodes.com/quality/product-change-notices/diodes-product-change-notices/				
For More Information Contact:	http://www.diodes.com/contacts.html				
Data Sheet:	http://www.diodes.com/catalog				
DISCLAIMER					

Unless a Diodes Incorporated Sales representative is contacted in writing within 30 days of the posting of this notice, all changes described in this announcement are considered approved.



Table 1: Additional Assembly and Test Site, Tianshui Huatian Electronic Group Co., Ltd. (HTME) in China							
SBR10100CT	SBR20A40CT	SBR20U100CT	SBR40150CT	SBR10100CTB-13	SBR20A100CTB		
SBR10U100CT	SBR20A100CT	SBR30A60CT	SBR30A120CT	SBR20100CTB-13	SBR20A100CTB-13		
SBR20100CT	SBR20U60CT	SBR30A100CT	SBR20A120CT				
	rent POD listed in the			nbined POD will be listed			
Baseline POD (Diodes internal Shanghai Assembly & Test Site (SAT)							
	Baseline TO220AF	3	Combined TO220	Combined TO220AB: Option A (SAT-Baseline) + Option B (HTME)			
	TO220AB .1		₩E₩	TOZZONO JI	a		
D D D D D D D D D D D D D D D D D D D	A P A P A P A P A P A P A P A P A P A P	Dim Min Max Typ. 1  A 36, 482 - 1  A1 0.51 1.39 - 1  A2 2.04 2.92 - 1  D. 0.39 1.01 0.81 0  D2 1.15 1.77 1.24 0  D. 1422 16.51 - 1  D1 8.39 10.21 - 1  D2 11.50 10.85 0.8  E1 6.86 8.83 - 1  E1 5.86 8.83 - 1  L1 2.70 14.73 - 1  L1 8.84 2.8 1  L1 1.84 4.08 - 1  A1 Dimensions in mm	Copion A (Top View) (Top View)	Option A (Sustain View)	TO220AB .  Dim Min J Max 1 702.  A 3 561 4 822 .  A 1 0.51 1 332 .  A 2 2 0.4 2 822 .  b 0.389 1.01 0.81 0.81 0.22 1.15 1.77 1.24 0.0 0.00 0.00 0.00 0.00 0.00 0.00 0.		
	rent POD listed in the les internal Shanghai Ass		Change To: Combined POD will be listed in the device datasheet				
Daseline POD (Dioc	Baselinet TO263Al	•	Combined POD (SAT + HTME) remains the same  Combined TO263AB: Option A (SAT-Baseline)+ Option B (HTME)				
	TO263AB (D2PAK		22221100 10201	· · · · · · · · · · · · · · · · · · ·	(111111)		
Detail B	See Detail B	TO263AB (D2PAK)  Dim Min Max Typ  A 4.07 4.82 -  A1 0.00 0.25 -  b 0.51 0.99 -  b2 1.15 1.77 -  c 0.356 0.73 -  c2 1.143 1.65 -  D 8.39 9.65 -  D1 6.55 6.95 -  e 2.54 Typ  E 9.66 10.66 -  E1 6.23 8.23 -  H 14.61 15.87 -  L 1.78 2.79 -  L1 - 1.67 -  L2 - 1.77 -  L3 0.254  a 0" 8" -  All Dimensions in mm	Option A (Top View) (Top View)	Et J J J J J J J J J J J J J J J J J J J	TO263AB    Dim   Min   Max   Typ     A   4.07   4.82   -     A1   0.00   0.25   -     b   0.51   0.99   -     b2   1.15   1.77   -     c   0.365   0.73   -     c2   1.143   1.65   -     D   8.39   9.65   -     e   2.54 TYP     E   9.66   10.66   -     E1   6.23   8.23   -     H   14.61   15.87   -     L   1.78   2.79   -     L1   - 1.67   -     L2   - 1.77   -     L3   -   0.254     a   0°   8°   -     All Dimensions in mm		

Table 2: Additional assembly and test site, Eris Technology Corp. (ERIS) in Taiwan							
MBR2150VRTR-G1	MBR3100VRTR-G1	APD240VRTR-G1	APD340VRTR-G1	APD260VRTR-G1			

Rel Date: 2/10/2016